

# High Performance Computing for Silicon Design

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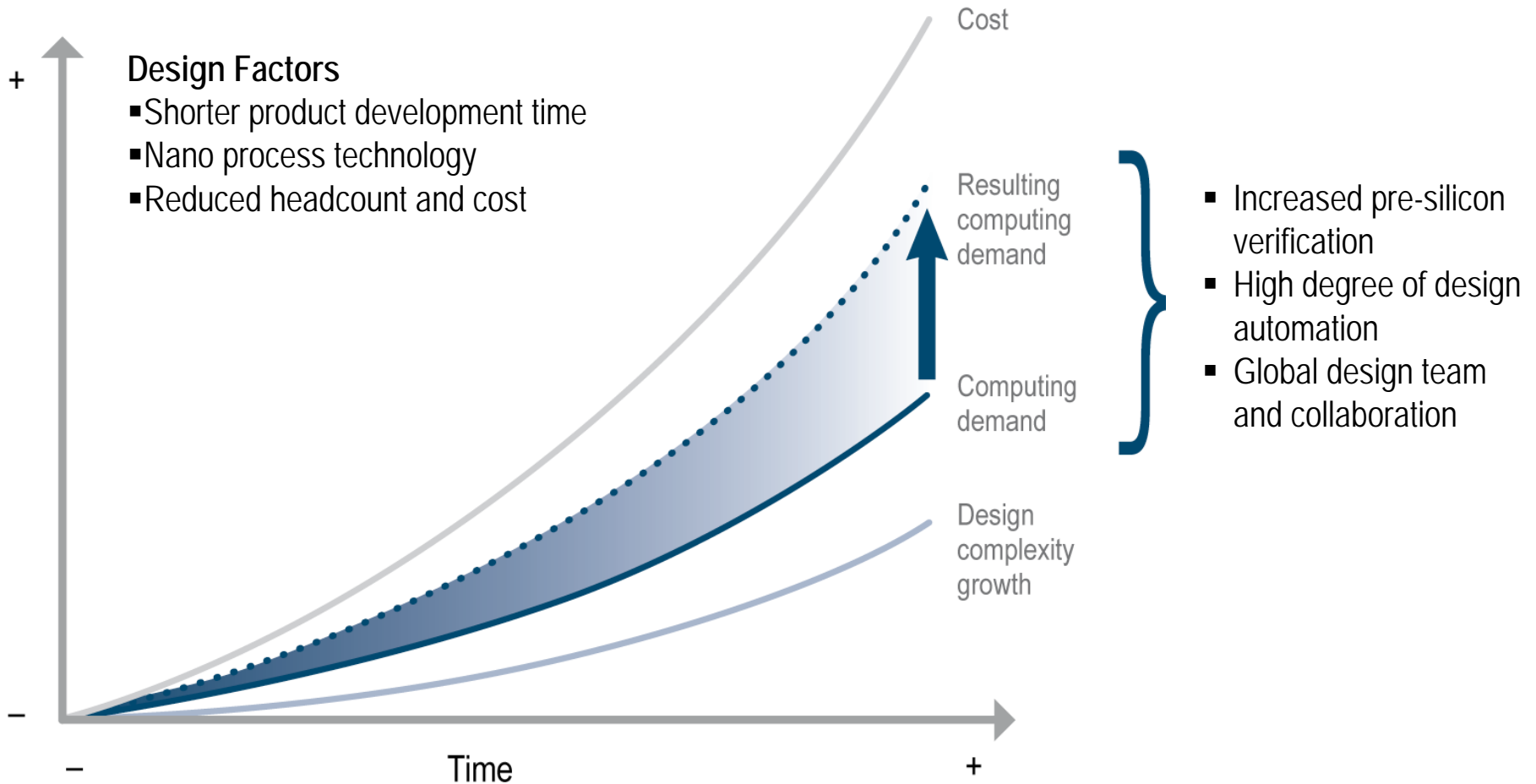
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# Intel Computing Environment and Computing Demand



# Design Team Challenges



# Intel Data Center Profile

- Intel has four major groups currently driving individual data center requirements (DOME):
  - (**D**esign) Design Computing: Support the chip design community and they have most of the servers within Intel
  - (**O**ffice) General Purpose: Supporting typical IT and customer services
  - (**M**anufacturing) FAB/ATM: Manufacturing computing supporting fabrication and assembly
  - (**E**nterprise) Enterprise applications supporting eBiz

70% of servers in Intel are in “D”  
30% of servers are in “OME”



# Design Computing Env Overview

- Classification by server type in “D” environment
  - 65,000 Servers running Linux
  - 52% Blades (Xeon 2S) – All multi-core servers are at 4GB-8GB per core
  - 42% 1U (Xeon 2S, Few 1S) – Multi-core servers are at 8GB per core
  - 6% Rest (Xeon MP) – 128GB to 1TB per server
- Classification by use model in “D” environment
  - Batch servers (70%)
  - Interactive & large memory batch servers (30%)
- High Performance Mega Data Centers:
  - Each data center has multiple modules design to handle over 500+ watts/SF
  - 6000 sq ft/ per module with ~3MW of useable power
  - ~200 cabinets/racks per module
  - 15-22KW power allocation per rack (48-64 blades per rack)
  - Some data centers support 30KW (Up to 84 blades per rack)

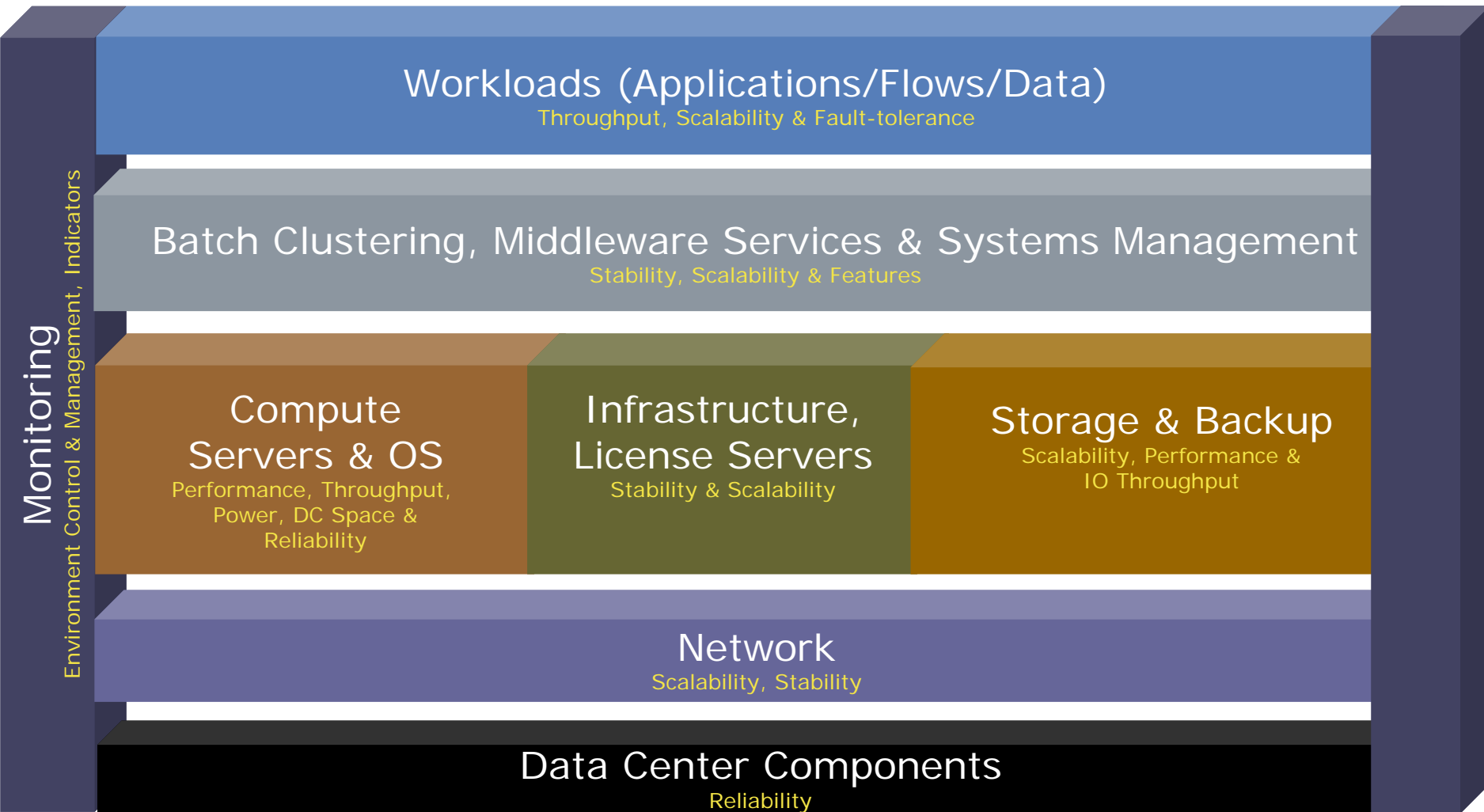
# Compute Demand Drivers inside Intel

- Pre-Silicon Design Computing
  - More than 100,000 simulation jobs per chip design each week for several quarters till tape-in
  - Small, Medium, Large memory workloads
  - Many chip designs in flight at a given time
  - Primarily CPU, and Physical Memory Bound – Lately Storage is of concern
- Tape-out Computing
  - 16,000 Optical Proximity Correction (OPC) jobs for each of the complex silicon layer
  - Small, Large, Very Large memory workloads
  - CPU, Network, and Storage Bound

# Intel HPC Environment



# HPC Solution Stack



# HPC Capability and Target Use Roadmap

	2006	2007	2008	2009	2010
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HPC Technology Areas	HPC-1 Optimize for 45nm, Support >=65nm	HPC-2 Optimize for 32nm, Support >=45nm	HPC-3 Target Additions Optimize for 22nm, Support >=32nm
Batch Clustering Stability, Scalability, Features	Systems/Pool: 8.5K ( <b>1.3x</b> )	11K ( <b>1.3x</b> )	11K ( <b>1x</b> )
	Jobs/Pool: 20K+ ( <b>1.5x</b> )	30K+ ( <b>1.5x</b> )	60K+ ( <b>2x</b> )
	Scheduling: Preferential	Smart Class	Support for Virtualization
Storage & Backup Scalability, Performance IO Throughput	IO Spec TP#: 5,120 ( <b>10x</b> )* HVM IO TP# : 3,200+MBps Volume Size : 3.2TB ( <b>8x</b> )	5,120 3,500+ MBps ( <b>1.1x</b> ) 6.4TB ( <b>2x</b> )	14,080 ( <b>2.75x</b> ) 5,300+ MBps ( <b>1.5x</b> ) TBD
	Single-Stream Perf*: 70MBps ( <b>1x</b> )	160 MBps ( <b>2.3x</b> )	240 MBps ( <b>1.5x</b> )
	HW/SW: Parallel-Storage-Gen1 <sup>§</sup>	Parallel-Storage-Gen2 <sup>§</sup>	Parallel-Storage/Open-Standard
Network Scalability, Stability	Storage: 40Gbps ( <b>10x</b> )	40Gbps ( <b>1x</b> )	11x1x10Gbps ( <b>2.75x</b> )
	Master: 1Gbps ( <b>10x</b> )	2x1Gbps ( <b>1x, Redundancy</b> )	10Gbps ( <b>5x</b> )
	Slave: 100Mbps ( <b>1x</b> )	100Mbps ( <b>1x</b> )	100Mbps/1Gbps ( <b>1x/10x</b> )
Compute Optimized for Perf, Throughput, Capacity Power & DC Space	Large RAM: <b>512GB (4x)</b> <small>(Based on Intel Architecture)</small> Perf. TP#: 1.6-5x	<b>1TB (2x)</b> <small>(Based on Intel Architecture)</small> 1.7x	TBD
	Batch Node: 2S/ <b>Dual</b> -Core/16GB Perf. TP: <b>2.1x</b> <small>(With Intel® Xeon® Processor 5150)</small>	2S/ <b>Quad</b> -Core/32GB <b>2.3x</b> <small>(With Intel® Xeon® Processor E5450)</small>	2S/ <b>Quad</b> -Core/48GB <b>1.74x</b> <small>(With Intel® Xeon® Processor X5570 – No HT)</small>
OS New HW Feature Support, Scalability, Stability, Perf.	Enterprise Feature: <b>Stable</b> , Inter-System <b>NUMA</b> Support	<b>Multi-Core</b> Optimized	<b>Virtualization</b> Optimized
License Servers Stability, Scalability	Platform: IA Based ( <b>3x</b> over RISC)	Latest IA based solution	Latest IA based solution
Apps Tuning Throughput	Tuning: CPU Prefetch ( <b>1.2x</b> ) Enablement: <b>512GB Support</b>	SSE4	Hyper-Threading

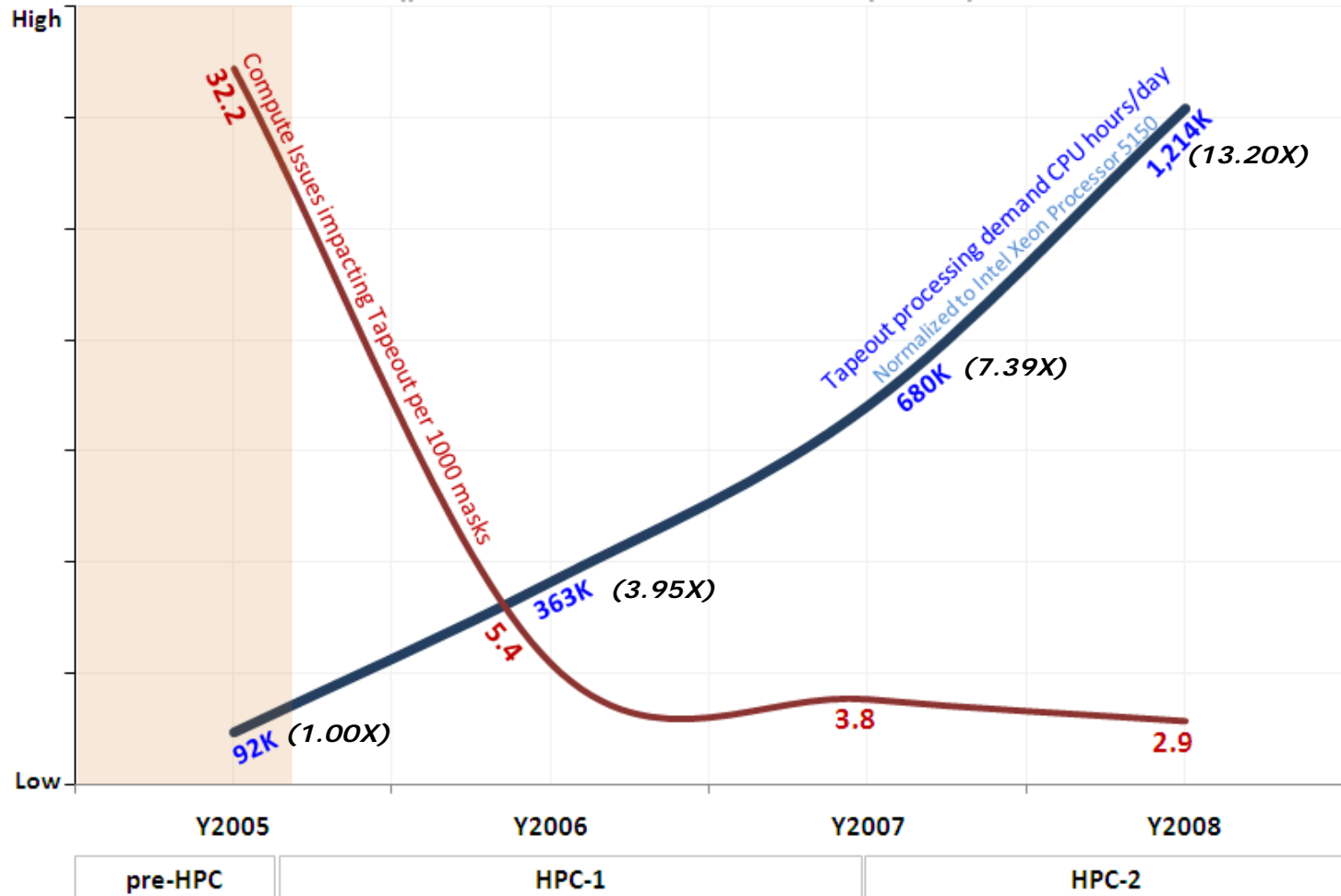
(10x)\* = 10x Spec Limit improvement over prior gen. solution (5120 MBps vs. 512MBps);  
 \*Single-Stream Performance" is relevant for Backup & Vol. size; <sup>§</sup> Proprietary Software  
 # TP – Throughput; HWA – Hardware Acceleration



# HPC Demand & Benefits for Intel Tapeout

## Intel Tapeout Computing Metrics

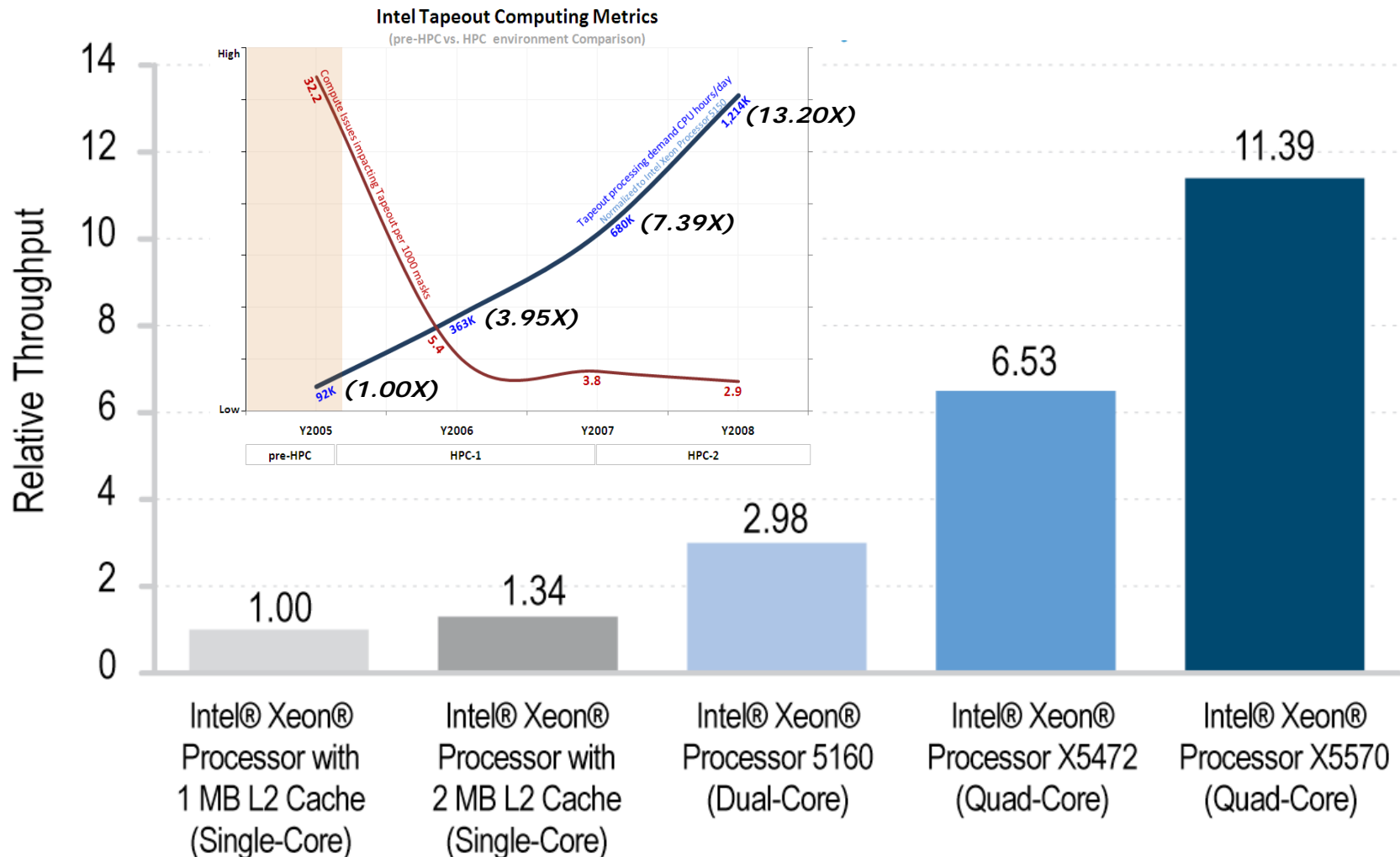
(pre-HPC vs. HPC environment Comparison)



# EDA Performance Improvement with Intel® Xeon® Processor Generations



# Intel® Architecture Performance Improvement for OPC



Intel internal measurements May 2007, November 2007, and February 2009.

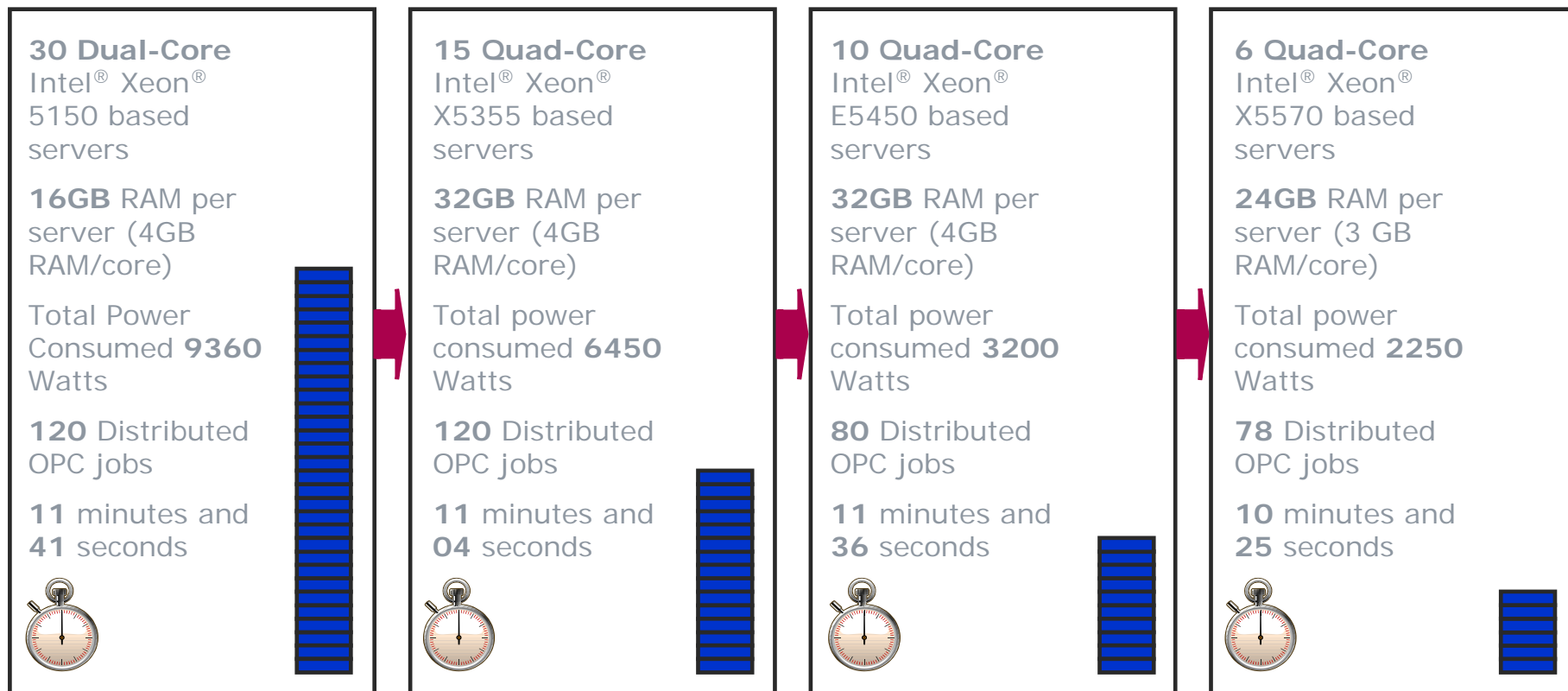


# Runtime Performance for OPC Application

Processor	OPC Jobs <sup>§</sup>	Runtime (HH:MM:SS)	Relative Throughput
64-bit Intel® Xeon® Processor with 1 MB L2 Cache (3.6 GHz)	2	10:40:12	1.00
64-bit Intel® Xeon® Processor with 2 MB L2 Cache (3.8 GHz)	2	07:58:31	1.34
Intel® Xeon® Processor 5160 (3.0 GHz)	4	03:34:39	2.98
Intel® Xeon® Processor X5472 (3.0 GHz)	8	01:37:58	6.53
Intel® Xeon® Processor X5570 (2.93 GHz)	8	00:56:11	11.39

<sup>§</sup> One OPC job per core.

# Intel Xeon processor 5500 series offers Higher Density, Superior Performance, and Lower Power for OPC



Intel quad-core server solution shows OPC throughput advantages

# Profile: Intel® Xeon® Processor 5500 Series

- Up to 13.14x improved performance over single-core processors for simulation workloads
- Up to 11.39x improved performance over single-core processors for OPC workloads
- Up to 13:1 server consolidation ratio for simulation workloads and 11:1 for OPC workloads



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Intel Information Technology

## Improving EDA Batch Application Performance

Intel® Xeon® processor 5500 series has demonstrated a substantial performance multiple versus comparable single generation Intel® quad-core processors in high-performance computing applications.

Dr. Howard Ho

Multi-core Single-chip processor architectures are used in a wide range of applications ranging from server-based applications to embedded systems. Intel® multi-core processors provide a significant performance advantage for a wide range of applications. The standard server-based Intel® multi-core processors...

- Profile: Intel® Xeon® Processor 5500 Series**
- Up to 13.14x improved performance over single-core processors for simulation workloads
  - Up to 11.39x improved performance over single-core processors for OPC workloads
  - Up to 13:1 server consolidation ratio for simulation workloads and 11:1 for OPC workloads

Figure 1 and Figure 2 show the performance improvement of Intel® multi-core processors in simulation and OPC applications. The performance improvement is measured in terms of the number of servers required to complete the same workload. The performance improvement is measured in terms of the number of servers required to complete the same workload. The performance improvement is measured in terms of the number of servers required to complete the same workload.

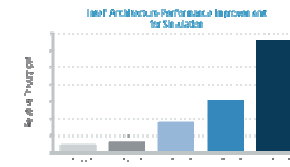


Figure 1. Servers based on Intel® Xeon® processor 5500 series improved Synopsys VCS® application performance for simulation.

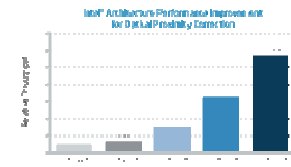
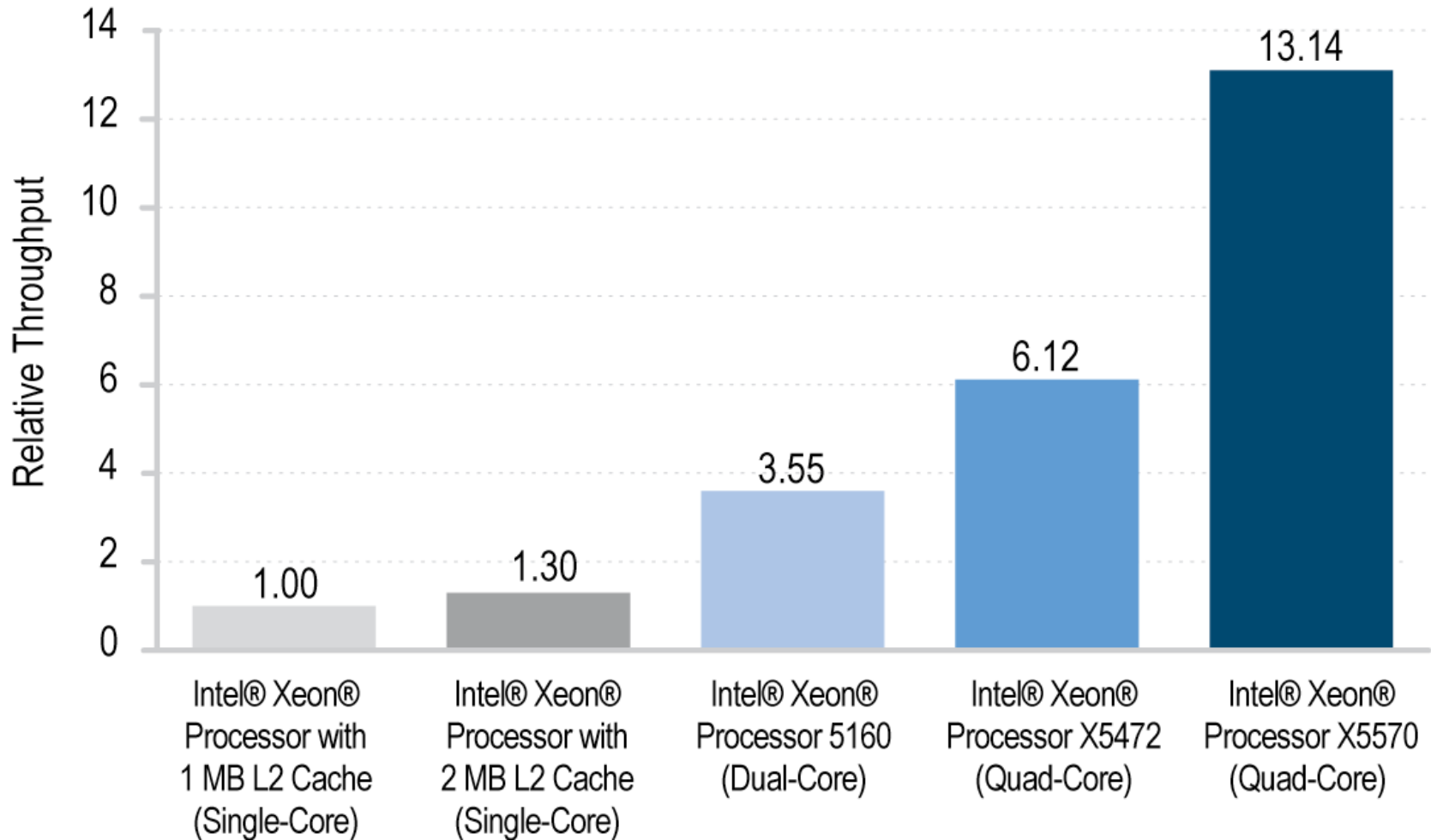


Figure 2. Servers based on Intel® Xeon® processor 5500 series improved Synopsys Proton® application performance for optical proximity correction (OPC).

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# Intel® Architecture Performance Improvement for Simulation



Intel internal measurements May 2007, November 2007, and February 2009.



# Runtime Performance for Simulation Application

Processor	Simultaneous Simulation Jobs	Runtime (HH:MM:SS)	Relative Throughput
64-bit Intel® Xeon® Processor with 1 MB L2 Cache (3.6 GHz)	2	93:51:07	1.00
64-bit Intel® Xeon® Processor with 2 MB L2 Cache (3.8 GHz)	2	72:23:11	1.30
Intel® Xeon® Processor 5160 (3.0 GHz)	4	26:26:16	3.55
Intel® Xeon® Processor X5472 (3.0 GHz)	8	15:20:01	6.12
Intel® Xeon® Processor X5570 (2.93 GHz) <sup>Δ</sup>	16	07:08:36	13.14

<sup>Δ</sup> Tests run on Intel Xeon Processor X5570 series had Intel® Hyper-Threading Technology and Intel® Turbo Boost Technology enabled.

# Mainstream Intel® Xeon® Processor 5500 Series Segments

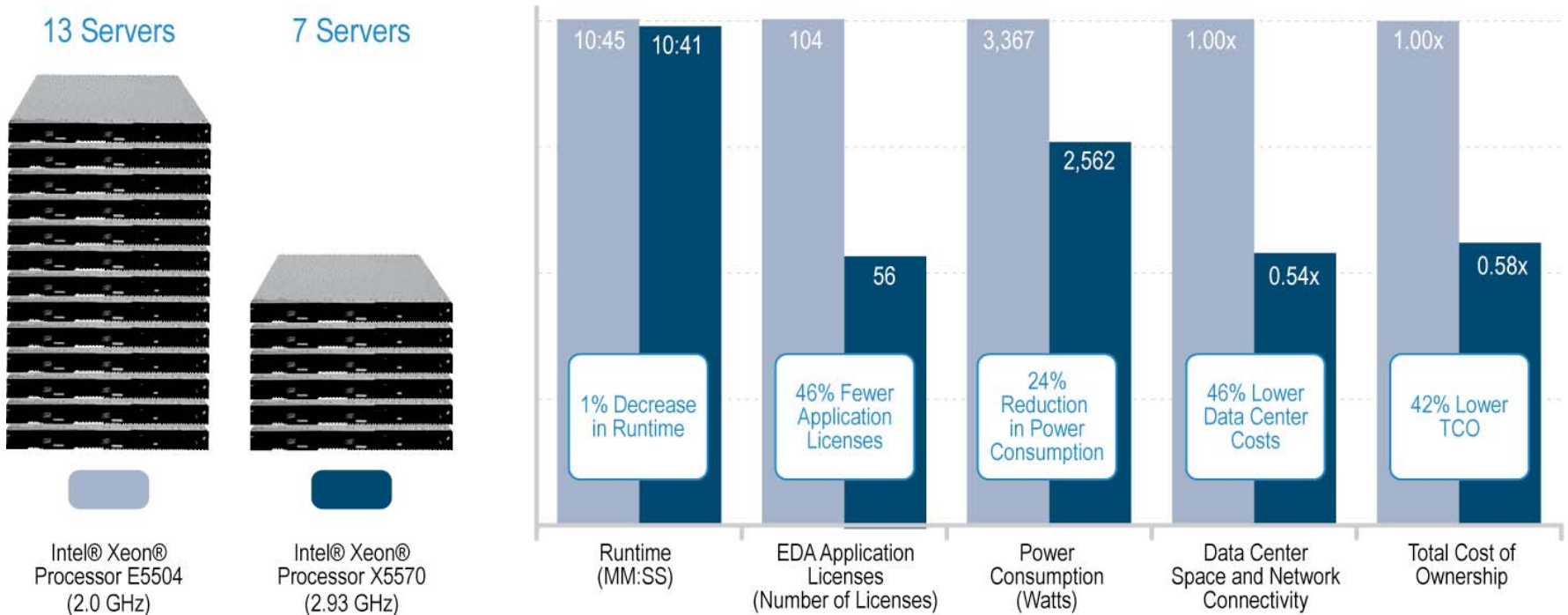
	Basic	Standard	Advanced
CPU Frequency	2.0 GHz to 2.13 GHz	2.26 GHz to 2.53 GHz	2.66 GHz to 2.93 GHz
CPU Power	80 W	80 W	95 W
QPI	4.8 GT/S	5.86 GT/S	6.4 GT/S
CPU Cache Size	4 MB	8 MB	8 MB
Memory Speed	800 MHz	800/1066 MHz	800/1066/1333 MHz
Intel® Turbo Boost Technology	No	Yes	Yes
Intel® HT Technology	No	Yes	Yes

GT/S – Gigatransfers/Second; Intel® HT – Intel® Hyper-Threading Technology; QPI – Intel® QuickPath Interconnect



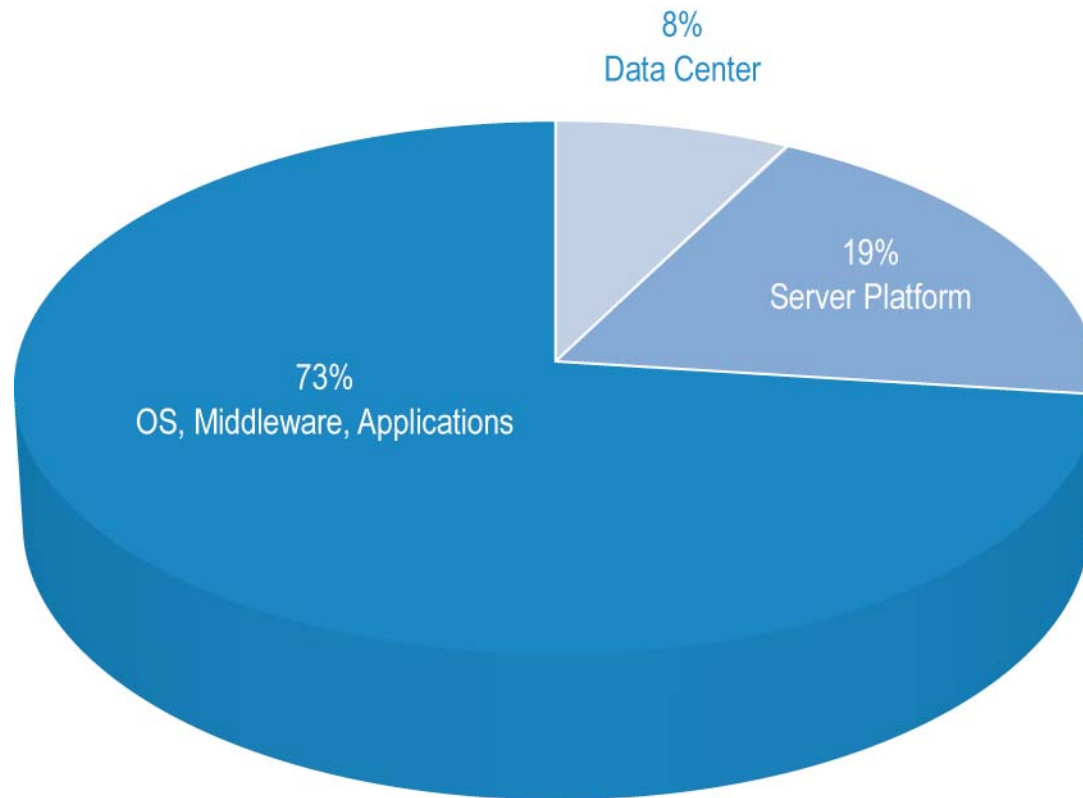
# EDA Throughput and Total Cost of Ownership

- In tests with real Intel EDA workloads, we required fewer servers based on high-end processors to achieve the same performance. This resulted in fewer EDA application licenses; reduced data center power, space, and connectivity requirements; and substantially lower estimated TCO.



# Server TCO

- The hardware platform accounts for a small proportion of server total cost of ownership (TCO). TCO calculations based on Intel® Xeon® processor X5570 (2.93 GHz).



# Profile: Intel® Xeon® Processor 5500 Series



- High-end processors reduce server TCO by 42 percent compared to low-end processors
- High-end processors deliver up to 87 percent faster performance

IT@Intel Brief  
Intel Information Technology

## Selecting Server Processors to Reduce Total Cost

With the introduction of the Intel® Xeon® processor 5500 series-based platforms, the benefits we are seeing from our IT strategy to standardize on higher-end processors for our servers purchases is even more compelling and results in a significantly lower TCO.

— Dave Dugan

Intel's standardizing on higher-end processors for its servers is a key step in reducing its total cost of ownership (TCO) for its servers. In fact, Intel's standardizing on higher-end processors for its servers is a key step in reducing its total cost of ownership (TCO) for its servers. In fact, Intel's standardizing on higher-end processors for its servers is a key step in reducing its total cost of ownership (TCO) for its servers.

### Profile: Intel® Xeon® Processor 5500 Series

- High-end processors reduce server TCO by 42 percent compared to low-end processors
- High-end processors deliver up to 87 percent faster performance

Compared to the Intel® Xeon® processor 3500 series, the Intel® Xeon® processor 5500 series delivers up to 87 percent faster performance in some key applications. This is due to the higher clock speeds and larger caches of the Intel® Xeon® processor 5500 series. In addition, the Intel® Xeon® processor 5500 series is designed to be more power-efficient, which helps to reduce the total cost of ownership (TCO) of the server. This is achieved through a combination of factors, including the use of more efficient power supplies and the use of more efficient cooling solutions.

Other system stakeholders benefit from the use of higher-end processors. For example, the use of higher-end processors can help to reduce the total cost of ownership (TCO) of the server by reducing the need for additional hardware. This is achieved through a combination of factors, including the use of more efficient power supplies and the use of more efficient cooling solutions.

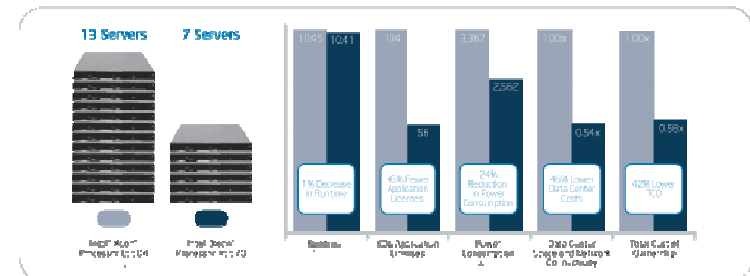


Figure 1. Electronic design automation (EDA) throughput and total cost of ownership (TCO).

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# HPC-1 to HPC-2 Storage Performance

HPC-2 Generation Limit: ~**15K** OPC jobs accessing one Parallel-Storage

Category	Parallel-Storage-Gen1	Parallel-Storage-Gen2
Meta Data Server Load	~100%	~80%
Interactive Latency	Unacceptable	Acceptable (no impact)
Write (sec)	25.00	4.00 (6.25x)
Read (sec)	25.00	0.47 (53x)
File listing (sec)	17.00	0.7 (24x)
File removal (sec)	25.00	0.36 (69x)
Event: Storage Vol Offline	Yes	No

